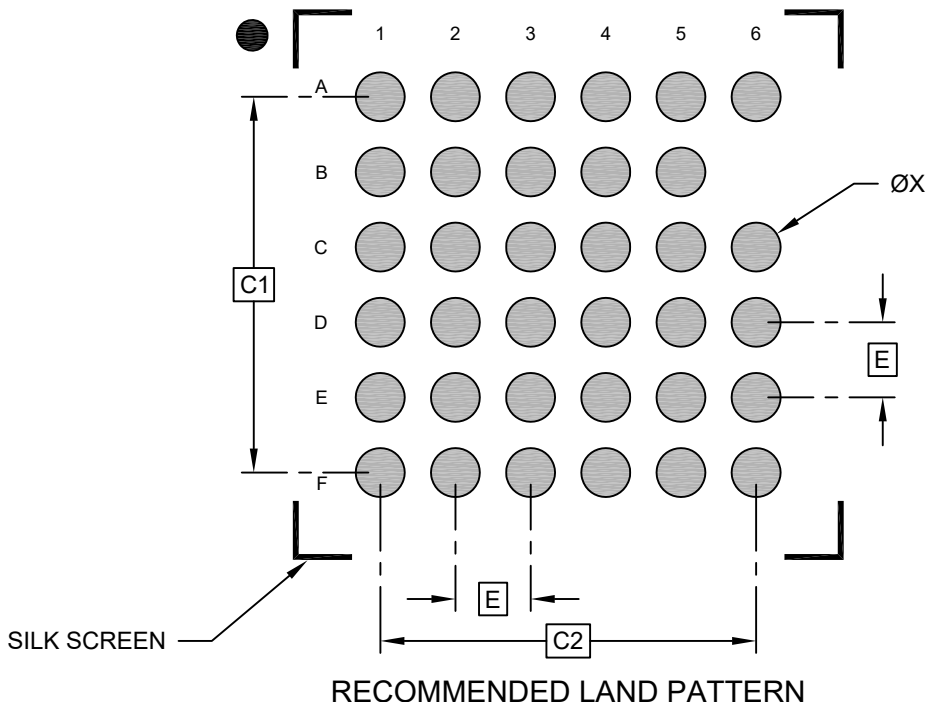


35-Ball Wafer Level Chip Scale Package (FQB) - 2.821x2.529 mm Body [WLCSP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		MILLIMETERS		
Units		MIN	NOM	MAX
Dimension Limits				
Contact Pitch	E	0.40 BSC		
Contact Pad Spacing	C1	2.00 BSC		
Contact Pad Spacing	C2	2.00 BSC		
Contact Pad Diameter (X35)	X	0.26		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.